

CLAIM AMENDMENTS

1. (currently amended) An on-chip inductor consisting of:

~~at least one~~ a dielectric layer;

~~at least one~~ a conductive winding on the ~~at least one~~ dielectric layer; and

a P-well having a major surface parallel to a major surface of the dielectric layer; and

a substrate having a major surface parallel to the major surface of the dielectric layer.

2. (currently amended) ~~The on-chip inductor of claim 1 further consists of~~ An on-chip inductor consisting of:

a dielectric layer;

a conductive winding on the dielectric layer;

a P-well having a major surface parallel to a major surface of the dielectric layer;

a field oxide having a major surface that is juxtaposed to the major surface of the P-well;
and

a substrate having a major surface parallel to the major surface of the dielectric layer.

3. (currently amended) The on-chip inductor of claim 1 ~~further consists of~~ wherein:

~~the at least one dielectric layer including one layer; and~~

~~the at least one conductive winding including is a spiral winding on the one layer.~~

4 - 8. (canceled).

9. (currently amended) An on-chip inductor consisting of:

~~at least one~~ a dielectric layer;

~~at least one~~ a conductive winding on the at least one dielectric layer; ~~and~~

a field oxide layer having a major surface parallel to a major surface of the dielectric layer; and

a substrate having a major surface parallel to the major surface of the dielectric layer.

10 -30. (canceled)